

Title (en)
ADHESIVE AGENT FOR HIGH-FREQUENCY INDUCTION HEATING

Title (de)
HAFTMITTEL FÜR HOCHFREQUENZ-INDUKTIONSERWÄRMUNG

Title (fr)
AGENT ADHÉSIF POUR CHAUFFAGE PAR INDUCTION À HAUTE FRÉQUENCE

Publication
EP 4155359 A1 20230329 (EN)

Application
EP 21832292 A 20210625

Priority

- JP 2020113564 A 20200630
- JP 2020113539 A 20200630
- JP 2021010550 A 20210126
- JP 2021024196 W 20210625

Abstract (en)
An adhesive agent for high-frequency dielectric heating (adhesive sheet 1A) at least contains a thermoplastic resin (A) and a dielectric filler (B) that generates heat upon application of a high-frequency electric field. The thermoplastic resin (A) at least contains a first thermoplastic resin (A1) and a second thermoplastic resin (A2). The thermoplastic resin (A1) is a silane-modified thermoplastic resin. The second thermoplastic resin (A2) is a thermoplastic resin that is not silane-modified.

IPC 8 full level
C09J 11/04 (2006.01); **B29C 65/32** (2006.01); **B29C 65/36** (2006.01); **C09J 7/35** (2018.01); **C09J 123/04** (2006.01); **C09J 123/10** (2006.01); **C09J 123/26** (2006.01); **C09J 201/02** (2006.01)

CPC (source: EP US)
B29C 65/04 (2013.01 - EP); **B29C 65/32** (2013.01 - EP); **B29C 65/36** (2013.01 - EP); **C09J 7/35** (2018.01 - US); **C09J 9/00** (2013.01 - EP); **C09J 9/02** (2013.01 - US); **C09J 11/04** (2013.01 - EP); **C09J 151/06** (2013.01 - EP); **C09J 201/10** (2013.01 - EP); **C08K 3/013** (2018.01 - EP); **C08K 3/14** (2013.01 - EP); **C08K 2003/2237** (2013.01 - EP); **C08K 2003/2296** (2013.01 - EP); **C09J 2301/304** (2020.08 - US); **C09J 2301/408** (2020.08 - US); **C09J 2423/04** (2013.01 - US); **C09J 2423/10** (2013.01 - US)

C-Set (source: EP)
C09J 201/10 + C08L 101/02

Designated contracting state (EPC)
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)
BA ME

Designated validation state (EPC)
KH MA MD TN

DOCDB simple family (publication)
EP 4155359 A1 20230329; **EP 4155359 A4 20240724**; CN 115867624 A 20230328; JP WO2022004606 A1 20220106;
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EP 21832292 A 20210625; CN 202180047055 A 20210625; JP 2021024196 W 20210625; JP 2022533962 A 20210625;
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